SSD1685

Product Proposal

168 /184 /200 /216 Source x 384 Gate

Red/Black/White **Active Matrix EPD Display Driver with Controller**



Oct 2020

Appendix: IC Revision history of SSD1685 Specification

Version	Change Items	Effective Date
0.10	Initial Release	18-Jun-2020
0.11	Bemoved the 0.47uF value for C8 from component list (Table 12-1)	22-Oct-2020

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1 GENERAL DESCRIPTION

SSD1685 is an Active Matrix EPD display driver with controller for Red/Black/White EPD displays.

It consists of selectable 168/184/200/216 number of source outputs, 384 gate outputs, 1 VCOM and 1VBD (for border), which can support displays with resolution up to 216 x 384.

In the SSD1685, data and commands are sent from MCU through hardware selectable serial peripheral interface. It has embedded booster, regulator and oscillator which is suitable for EPD display applications.

2 FEATURES

- Design for dot matrix type active matrix EPD display, support Red/Black/White color
- Selectable number of source outputs for 168/184/200/216, 384 gate outputs, 1 VCOM and 1VBD (for border)
- Power supply:
 - VCI: 2.2 to 3.7V
 - VDDIO: Connect to VCI
 - VDD: 1.8V, regulate from VCI supply
- Maximum on chip display RAM:
 - Mono B/W: 216x384 bits
 - Mono Red: 216x384 bits
- On-chip booster and regulator for generating VCOM, Gate and Source driving voltage
- Gate driving output voltage: 2-level outputs (VGH, VGL), Max 40Vp-p
 - VGH: 10V to 20V (Voltage adjustment step: 500mV)
 - VGL: -VGH (Voltage adjustment step: 500mV)
- Source driving output voltage: 4-levels outputs (VSH1, VSH2, VSS and VSL)
 - VSH1: 8.8V to 17V (Voltage adjustment step: 200mV)
 - VSH2: 2.4V to 17V (Voltage adjustment step: 100mV for 2.4V to 8.6V, 200mV for 8.8V to 17V)
 - VSL: -5V to -17V (Voltage adjustment step: 500mV)
- VCOM output voltage
 - DCVCOM: -3.0V to -0.2V in 100mV resolution
 - ACVCOM: 3-level outputs (VSH1+DCVCOM, DCVCOM, VSL+DCVCOM)
- On-chip oscillator, adjustable frame rate from 25Hz to 100Hz
- Programmable output Waveform Settings:
 - Individual setting of 4 LUT [LUTC, LUTB, LUTW, LUTR]
 - VS: 2-bit per 4 phases
 - Individual setting of 4 LUT
 - 32 phases (4 phases/group, 8 groups with repeat and state repeat function)
 - TP: Max. 63 frame/phase
 - RP: 0 to 255 times for repeat count
 - SR: 0 to 255 times for state repeat count; state repeat count for phase A,B and 1 state repeat count for phase C,D
 - XON: All Gate On Selection for each phase A,B and phase C,D
- Embedded OTP to store the waveform settings and parameters:
 - 24 sets of Waveform Settings (WS) including
 - waveform look up table (LUT)
 - Gate/Source voltage
 - VCOM value
 - Frame Rate
 - Option for LUT end
 - 24 sets of Temperature Range (TR)
 - Display mode selection
 - 4-byte waveform version
 - 10-byte User ID
- Embedded OTP to store the initial code setting
- External or internal generated voltage for burning OTP
- Built-in CRC checking method for RAM content and WS & TR in OTP
- VCI low voltage detection
- Driving voltage ready detection
- Support display partial update

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- Auto write RAM command for regular patterns
- Internal Temperature Sensor of +/-2degC accuracy from -25degC to 50degC
- I2C single master interface to communicate with external temperature sensor
- MCU interface: 4-wire or 3-wire Serial peripheral interface (maximum SPI write speed 20MHz)
- Available in COG package

3 ORDERING INFORMATION

Table 3-1: Ordering Information

Ordering Part Number	Package Form	Remark
SSD1685Z	Gold Bump Die	Bump Face Up On Waffle pack Die thickness: 300um Bump height: 12um
SSD1685Z8	Gold Bump Die	Bump Face Down On Waffle pack Die thickness: 300um Bump height: 12um

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4 BLOCK DIAGRAM

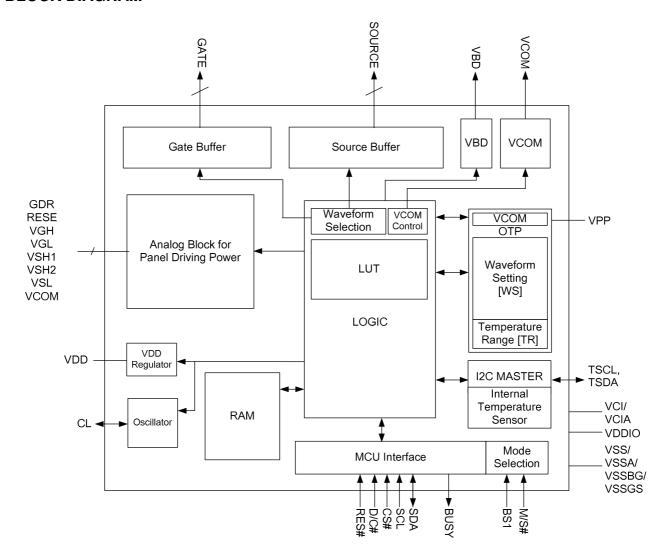


Figure 4-1: SSD1685 Block Diagram

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5 PIN DESCRIPTION

Key:

I = Input

O =Output

IO = Bi-directional (input/output)

P = Power pin

C = Capacitor Pin

NC = Not Connected

Table 5-1: Power Supply Pins

Name	Туре	Connect to	Function	Description	When not in use
VCI	Р	Power Supply	Power Supply	Power input pin for the chip.	-
VCIA	P	Power Supply	Power Supply	Power input pin for the chip Connect to VCI in the application circuit.	-
VDDIO	P	Power Supply	Power for interface logic pins	Power input pin for the Interface Connect to VCI in the application circuit.	-
VDD	P	Capacitor	Regulator output	Core logic power pin VDD can be regulated internally from VCI. A capacitor should be connected between VDD and VSS under all circumstances.	-
VSS	Р	VSS	GND	Ground (Digital).	-
VSSA	Р	VSS	GND	Ground (Analog) - Connect to VSS in the application circuit.	-
VSSBG	Р	VSS	GND	Ground (Reference) pin Connect to VSS in the application circuit.	-
VSSGS	Р	VSS	GND	Ground (Output) pin Connect to VSS in the application circuit.	-
VPP	Р	Power Supply	OTP power	Power Supply for OTP Programming.	Open

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Table 5-2: Interface Logic Pins

Name	Туре	Connect to	Function	Description	When not in use
SCL	I	MPU	Data Bus	This pin is serial clock pin for interface. Refer to MCU interface in Section 6.1.	-
SDA	I/O	MPU	Data Bus	This pin is serial data pin for interface. Refer to MCU interface in Section 6.1.	-
CS#	I	MPU	Logic Control	This pin is the chip select input connecting to the MCU. Refer to MCU interface in Section 6.1.	VDDIO or VSS
D/C#	I	MPU	Logic Control	This pin is Data/Command control pin connecting to the MCU. Refer to MCU interface in Section 6.1.	VDDIO or VSS
RES#	I	MPU	System Reset	This pin is reset signal input. Active Low.	-
BUSY	0	MPU	Device Busy Signal	This pin is Busy state output pin. When Busy is High, the operation of the chip should not be interrupted, and command should not be sent. For example., The chip would output Busy pin as High when - Outputting display waveform; or - Programming with OTP - Communicating with digital temperature sensor	Open
M/S#	I	VDDIO/VSS	Cascade Mode Selection	 This pin is Master and Slave selection pin. For the single chip application, the M/S# pin should be connected to VDDIO. In the cascade mode: For Master Chip, the M/S# pin should be connected to VDDIO. For Slave Chip, the M/S# pin should be connected to VSS. The oscillator, booster and regulator circuits of the slave chip will be disabled. The corresponding pins including CL, VDD, VDDIO, VGH, VGL, VSH1, VSH2, VSL and VCOM must be connected to the master chip. 	-
CL	I/O	NC	Clock signal	This pin is the clock signal pin. - For the single chip application, the CL pin should be left open. - In the cascade mode, the CL pin of the slave chip should be connected to the CL pin of the master chip.	-
BS	I	VDDIO/VSS	MCU Interface Mode Selection	This pin is for selecting 3-wire or 4-wire SPI bus. BS1 MCU Interface L 4-wire SPI H 3-wire SPI (9-bit SPI)	-
TSDA	I/O	Temperature sensor SDA	Interface to Digital Temp. Sensor	This pin is I ² C Interface to digital temperature sensor Data pin. External pull up resistor is required when connecting to I ² C slave.	VSS
TSCL	0	Temperature sensor SCL	Interface to Digital Temp. Sensor	This pin is I ² C Interface to digital temperature sensor Clock pin. External pull up resistor is required when connecting to I ² C slave.	VSS

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Table 5-3: Analog Pins

Name	Туре	Connect to	Function	Description	When not in use
GDR	0	POWER MOSFET Driver Control	VGH, VGL Generation	This pin is N-Channel MOSFET gate drive control pin.	-
RESE	I	Booster Control Input		This pin is Current sense input pin for the control Loop.	-
VGH	С	Stabilizing capacitor		This pin is Positive Gate driving voltage. Connect a stabilizing capacitor between VGH and VSS in the application circuit.	-
VGL	С	Stabilizing capacitor		This pin is Negative Gate driving voltage. Connect a stabilizing capacitor between VGL and VSS in the application circuit.	-
VSH1	С	Stabilizing capacitor	VSH1, VSH2, VSL Generation	This pin is Positive Source driving voltage, VSH1 Connect a stabilizing capacitor between VSH1 and VSS in the application circuit.	-
VSH2	С	Stabilizing capacitor		This pin is Positive Source driving voltage, VSH2 Connect a stabilizing capacitor between VSH2 and VSS in the application circuit.	
VSL	С	Stabilizing capacitor		This pin is Negative Source driving voltage. Connect a stabilizing capacitor between VSL and VSS in the application circuit.	-
VCOM	С	Panel/ Stabilizing capacitor	VCOM Generation	This pins is VCOM driving voltage Connect a stabilizing capacitor between VCOM and VSS in the application circuit.	-

Table 5-4: Driver Output Pins

Name	Туре	Connect to	Function	Description	When not in use
S [215:0]	0	Panel	Source driving signal	Source output pin.	Open
G [383:0]	0	Panel	Gate driving signal	Gate output pin.	Open
VBD	0	Panel	Border driving signal	Border output pin.	Open

Table 5-5: Miscellaneous Pins

Name	Туре	Connect to	Function	Description	When not in use
NC	NC	NC	Not Connected	This is dummy pin. It should not be connected with other NC pins.	Open
RSV	NC	NC	Reserved	This is a reserved pin and should be kept open.	Open
TPA, TPB, TPC, TPD, TPF, FB	NC	NC	Reserved for Testing	Reserved pins. - Keep open. - Do not connect to other NC pins and test pins including TPA, TPB, TPC, TPD, TPE, TPF, TIN and FB.	Open
TIN	I	TPE	Reserved for Testing	This is a reserved pin and should be connected to TPE pin	VSS/VDDIO
TPE	0	TIN	Reserved for Testing	This is a reserved pin and should be connected to TIN pin	Open

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6 Functional Block Description

6.1 MCU Interface

6.1.1 MCU Interface selection

The SSD1685 can support 3-wire/4-wire serial peripheral. MCU interface is pin selectable by BS1 shown in Table 6-1.

Table 6-1: Interface pins assignment under different MCU interface

		Pin Name					
MCU Interface	BS1	RES#	CS#	D/C#	SCL	SDA	
4-wire serial peripheral interface (SPI)	L	RES#	CS#	DC#	SCL	SDA	
3-wire serial peripheral interface (SPI) – 9 bits SPI	Н	RES#	CS#	L	SCL	SDA	

Note

6.1.2 MCU Serial Interface (4-wire SPI)

The 4-wire SPI consists of serial clock SCL, serial data SDA, D/C# and CS#. The control pins status in 4-wire SPI in writing command/data is shown in Table 6-2 and the write procedure 4-wire SPI is shown in Table 6-2

Table 6-2: Control pins status of 4-wire SPI

Function	SCL pin	SDA pin	D/C# pin	CS# pin
Write command	↑	Command bit	L	L
Write data	↑	Data bit	Н	L

Note:

- (1) L is connected to VSS and H is connected to VDDIO
- (2) ↑ stands for rising edge of signal
- (3) SDA (Write Mode) is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0. The level of D/C# should be kept over the whole byte. The data byte in the shift register is written to the Graphic Display Data RAM (RAM)/Data Byte register or command Byte register according to D/C# pin.

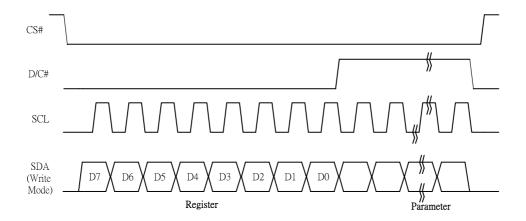


Figure 6-1: Write procedure in 4-wire SPI mode

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 $^{^{(1)}}$ L is connected to V_{SS} and H is connected to V_{DDIO}

In the read operation (Command 0x1B, 0x27, 0x2D, 0x2E, 0x2F, 0x35). After CS# is pulled low, the first byte sent is command byte, D/C# is pulled low. After command byte sent, the following byte(s) read are data byte(s), so D/C# bit is then pulled high. An 8-bit data will be shifted out on every clock falling edge. The serial data SDA bit shifting sequence is D7, D6, to D0 bit. Figure 6-2 shows the read procedure in 4-wire SPI.

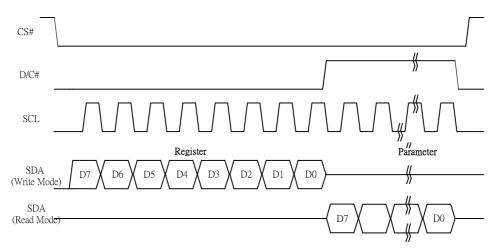


Figure 6-2: Read procedure in 4-wire SPI mode

6.1.3 MCU Serial Peripheral Interface (3-wire SPI)

The 3-wire SPI consists of serial clock SCL, serial data SDA and CS#. The operation is similar to 4-wire SPI while D/C# pin is not used and it must be tied to LOW. The control pins status in 3-wire SPI is shown in Table 6-3.

In the write operation, a 9-bit data will be shifted into the shift register on every clock rising edge. The bit shifting sequence is D/C# bit, D7 bit, D6 bit to D0 bit. The first bit is D/C# bit which determines the following byte is command or data. When D/C# bit is 0, the following byte is command. When D/C# bit is 1, the following byte is data. Table 6-3 shows the write procedure in 3-wire SPI

Function	SCL pin	SDA pin	D/C# pin	CS# pin
Write command	↑	Command bit	Tie LOW	L
Write data	↑	Data bit	Tie LOW	L

Table 6-3: Control pins status of 3-wire SPI

Note:

- (1) L is connected to V_{SS} and H is connected to V_{DDIO}
- (2) ↑ stands for rising edge of signal

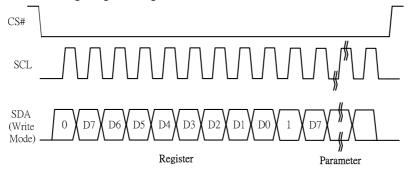


Figure 6-3: Write procedure in 3-wire SPI

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In the read operation (Register 0x1B, 0x27, 0x2D, 0x2E, 0x2F, 0x35). SDA data are transferred in the unit of 9 bits. After CS# pull low, the first byte is command byte, the D/C# bit is as 0 and following with the register byte. After command byte send, the following byte(s) are data byte(s), with D/C# bit is 1. After D/C# bit sending from MCU, an 8-bit data will be shifted out on every clock falling edge. The serial data SDA bit shifting sequence is D7, D6, to D0 bit. Figure 6-4 shows the read procedure in 3-wire SPI.

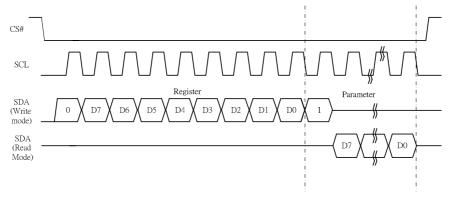


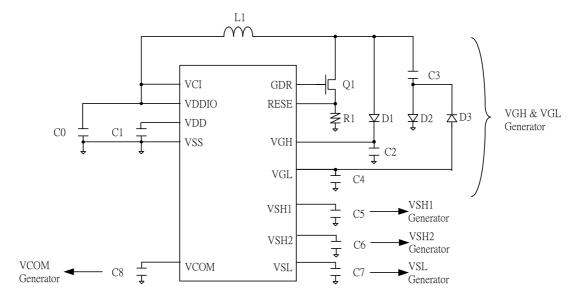
Figure 6-4: Read procedure in 3-wire SPI mode

6.2 OSCILLATOR

The oscillator module generates the clock reference for waveform timing and analog operations.

6.3 BOOSTER & REGULATOR

A voltage generation system is included in the driver. It provides all necessary driving voltages required for an AMEPD panel including VGH, VGL, VSH1, VSH2, VSL and VCOM. External application circuit is needed to make the on-chip booster & regulator circuit work properly.



6.4 VCOM SENSING

This functional block provides the scheme to select the optimal VCOM DC level. The sensed value can be programmed into OTP.

The flow of VCOM sensing:

- Active Gate is scanning during the VCOM sense Period.
- Source are VSS.
- VCOM pin used for sensing.
- During Sensing period, BUSY is high.
- After Sensing, Active Gate return to non-select stage.

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6.5 RAM

The On chip display RAM is holding the image data.

1 set of RAM is built for Mono B/W. The RAM size is 216x384 bits.

1 set of RAM is built for Mono Red. The RAM size is 216x384 bits.

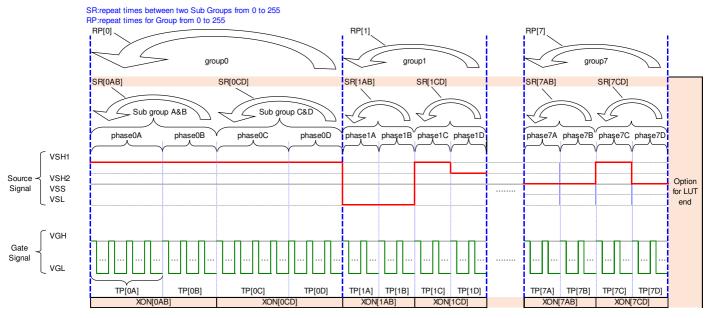
Table 6-4: RAM bit and LUT mapping for 3-color display

Data bit in R RAM	Data bit in B/W RAM	Image Color	LUT
0	0	Black	LUTB for driving Black
0	1	White	LUTW for driving White
1	0	Red	LUTR for driving Red

Table 6-5: RAM bit and LUT mapping for black/white display

Data bit in R RAM	Data bit in B/W RAM	Image Color	LUT
0	0	Black	LUTBB for driving Black
0	1	White	LUTWB for driving White
1	0	Black	LUTBW = LUTBB
1	1	White	LUTWW = LUTWB

6.6 Programmable Waveform for Gate, Source and VCOM



TP: time of phase length from 0 to 63* frames

0indicates phase skipped

TP, SR, RP are individual set for LUTC, LUTB, LUTW and LUTR

FR: Frame frequency selection

EOPT: Option for LUT end

XON: All Gate On selection for each nAB or nCD.

Figure 6-5: Gate waveform and Programmable Source and VCOM waveform illustration

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In the programmable waveform for Source and VCOM, there are 8 groups (Group0 to Group7) and each group has 4 phases (Phase A to Phase D) and 2 state repeats (Phase A and B, Phase C and D). Totally, there are 32 phases. In addition, in each phase, the phase length (TP[nX]) can be set by number of frame from 0 to 63 frames. Also, each group can be repeated with repeat counting number (RP[n]) from 0 to 255 times; each AB / CD phases can be repeated with state repeat counting number (SR[nAB]/SR[nCD]) from 0 to 255 times. For the voltage, there is four levels for Source voltage (VSS, VSH1, VSH2, VSL) and four levels for VCOM voltage (DCVCOM, VSH1+DCVCOM, VSL+DCVOM, Floating and VSS).

The description of each parameter is as follows.

- 1) TP[nX] represents the phase length set by the number of frame.
- The range of TP[nX] is from 0 to 63.
- n represents the Group number from 0 to 7; X represents the phase number from A to D.
- When TP[nX] = 0, the phase is skipped. When TP[nX] = 1, the phase is 1 frame, and so on. The maximum phase length is 63 frame.
- 2) RP[n] represents the repeat counting number for the Group.
- The range of RP[n] is from 0 to 255.
- n represents the Group number from 0 to 7.
- RP[n] = 0 indicates that the group is skipped, RP[n] = 1 indicates that the repeat times = 1, and so on. The maximum repeat times is 255.
- 3) SR[nAB] and SR[nCD] represent the state repeat counting number for Phase A & B and Phase C & D respectively.
- The range of SR[nXY] is from 0 to 255.
- n represents the Group number from 0 to 7.
- SR[nXY] = 0 indicates that the sub-group is skipped, SR[nXY] = 1 indicates that the repeat times = 1, and so on. The maximum repeat times is 255.
- 4) VS[nX-LUTm] represents Source and VCOM voltage level which is used in each phase. Table 6-6 shows the voltage settings for source voltage and VCOM voltage.
- n represents the Group number from 0 to 7.
- m represents the LUT number from 0-3.

Table 6-6: VS[nX-LUTm] settings for Source voltage and VCOM voltage

VS[nX-LUTm]	Source voltage	VCOM voltage
00	VSS	DCVCOM
01	VSH1	VSH1 + DCVCOM
10	VSL	VSL + DCVCOM
11	VSH2	Floating

5) FR indicates the frame rate

FR[3:0]	Frame Rate	FR[3:0]	Frame Rate
0001	25 Hz	1001	37.5 Hz
0010	50 Hz	1010	62.5 Hz
0011	75 Hz	1011	87.5 Hz
0100	100 Hz	1100	112.5 Hz
0101	125 Hz	1101	137.5 Hz
0110	150 Hz	1110	162.5 Hz
0111	175 Hz	1111	187.5 Hz
1000	200 Hz		

- 6) XON[nAB] and XON[nCD], indicates the gate scan selection.
- n represents the Group number from 0 to 7.
- XON[nXY] = 0 indicates Normal gate scan in Phase[nX] & Phase[nY].
- XON[nXY] = 1 indicates All gate on, that Gate keeps High until the phase for normal gate scan, in Phase[nX] & Phase[nY].

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6.7 WAVEFORM SETTING

As described in Section 6.6, parameters VS[nX-LUTm], TP[nX], RP[n], SR[nXY], FR[n] and XON[nXY] are used to define the driving waveform. In the SSD1685, there are 233 bytes in the waveform setting to store LUTB, LUTW, LUTR and LUTC, gate voltage, source voltage and frame rate. The waveform LUT of a particular temperature range can be loaded from OTP or written by MCU.

- WS byte 0~226, the content of VS[nX-LUTm], TP[nX], RP[n], SR[nXY], FR and XON[nXY] are defined by Register 0x32
- WS byte 227, the content of Option for LUT end, is the parameter belonging to register 0x3F.
- WS byte 228, the content of gate level, is the parameter defined by Register 0x03.
- WS byte 229~231, the content of source level, is the parameter defined by Register 0x04.
- WS byte 232, the content of VCOM level, is the parameter defined by Register 0x2C.

The SSD1685 waveform setting is shown in in Figure 6-6: Waveform Setting mapping

		vaveloilli setting is shown in in i gure t			
addr.	D7 D6	D5 D4 D3 D2 D1 D0	addr.	D7 D6	D5 D4 D3 D2 D1 D0
0		RP LUTC 0	112		RP LUTW 0
1	VS-0A-LUTC	TP LUTC 0A	113	VS-0A-LUTW	TP LUTW 0A
2	VS-0B-LUTC	TP LUTC 0B	114	VS-0B-LUTW	TP LUTW 0B
3	VS-0C-LUTC	TP LUTC 0C	115	VS-0C-LUTW	TP LUTW 0C
4	VS-0D-LUTC	TP LUTC 0D	116	VS-0D-LUTW	TP LUTW 0D
5	VO-0D-L010	SR LUTC 0AB	117	VO-OD-LOTW	SR LUTW 0AB
6		SR LUTC OCD	118		SR LUTW 0CD
7		RP LUTC 1	119		RP LUTW 1
8	VS-1A-LUTC	TP LUTC 1A	120	VS-1A-LUTW	TP LUTW 1A
9	VS-1B-LUTC	TP LUTC 1B	121	VS-1B-LUTW	TP LUTW 1B
10	VS-1C-LUTC	TP LUTC 1C	122	VS-1C-LUTW	TP LUTW 1C
11	VS-1D-LUTC	TP LUTC 1D	123	VS-1D-LUTW	TP LUTW 1D
	V3-1D-L010			VO-TD-LUTW	
12		SR LUTC 1AB	124		SR LUTW 1AB
13		SR LUTC 1CD	125		SR LUTW 1CD
14		RP LUTC 2	126		RP LUTW 2
50	VS-7A-LUTC	TP LUTC 7A	162	VS-7A-LUTW	TP LUTW 7A
51	VS-7A-LUTC	TP LUTC 7B	163	VS-7A-LUTW VS-7B-LUTW	TP LUTW 7B
52	VS-7C-LUTC	TP LUTC 7C	164	VS-7C-LUTW	TP LUTW 7C
53	VS-7D-LUTC	TP LUTC 7D	165	VS-7D-LUTW	TP LUTW 7D
54		SR LUTC 7AB	166		SR LUTW 7AB
55		SR LUTC 7CD	167		SR LUTW 7CD
56		RP LUTR 0	168		RP LUTB 0
57	VS-0A-LUTR	TP LUTR 0A	169	VS-0A-LUTB	TP LUTB 0A
58	VS-0B-LUTR	TP LUTR 0B	170	VS-0B-LUTB	TP LUTB 0B
	VS-0C-LUTR	TP LUTR 0C		VS-0C-LUTB	TP LUTB 0C
59	VS-UC-LUTR		171		
60	VS-0D-LUTR	TP LUTR 0D	172	VS-0D-LUTB	TP LUTB 0D
61		SR LUTR 0AB	173		SR LUTB 0AB
62		SR LUTR 0CD	174		SR LUTB 0CD
63		RP LUTR 1	175		RP LUTB 1
64	VS-1A-LUTR	TP LUTR 1A	176	VS-1A-LUTB	TP LUTB 1A
65	VS-1B-LUTR	TP LUTR 1B	177	VS-1B-LUTB	TP LUTB 1B
66	VS-1C-LUTR	TP LUTR 1C	178	VS-1C-LUTB	TP LUTB 1C
67	VS-1C-LUTR VS-1D-LUTR	TP LUTR 1D	179	VS-1D-LUTB	TP LUTB 1D
68	VO ID LOTT	SR LUTR 1AB	180	VO 18 2018	SR LUTB 1AB
		SR LUTR 1CD			SR LUTB 1CD
69			181		
70		RP LUTR 2	182		RP LUTB 2
)x04.		
			ννυ μ .		
106	VS-7A-LUTR	TP LUTR 7A	Settin	VS-7A-LUTB	TP LUTB 7A
107	VS-7B-LUTR	TP LUTR 7B	219	VS-7B-LUTB	TP LUTB 7B
108	VS-7C-LUTR	TP LUTR 7C	220	VS-7C-LUTB	TP LUTB 7C
109	VS-7D-LUTR	TP LUTR 7D	221	VS-7D-LUTB	TP LUTB 7D
	VO-1D-LUTR	SR LUTR 7AB		V3-7D-LU1B	SR LUTB 7AB
110			222		
111		SR LUTR 7CD	223		SR LUTB 7CD
			224		FR
			225		XON2CD XON2AB XON1CD XON1AB XON0CD XON0AB
			226	XON7CD XON7AB	XON6CD XON6AB XON5CD XON5AB XON4CD XON4AB
			227		EOPT
			228		VGH
			229		VSH1
			230		VSH2
			231		VSL
			232		VCOM

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6.8 Temperature Searching

The SSD1685 has internal temperature sensor to detect the environment temperature or can communicate with the external temperature sensor by I2C single master interface or can communicate with the external MCU to get the temperature value through SPI. In the SSD1685, there is a dedicated format for the temperature value so that the driver IC can understand it. The format of temperature value is described in Section 6.8.3.

6.8.1 Internal Temperature Sensor

The internal temperature sensor can be selected by command register. The accuracy of it is ±2degC from - 25degC to 50degC.

6.8.2 External Temperature Sensor I2C Single Master Interface

The driver IC can communicate with the external temperature sensor through I2C single master interface (TSDA and TSCL). TSDA will be SDA and TSCL will be SCL. TSDA and TSCL are required to connect with external pull-up resistor. Temperature register value of external temperature sensor can be read by command register.

6.8.3 Format of temperature value

The temperature value is defined by 8-bit binary. The rules are shown as below.

- If the Temperature value MSByte bit D11 = 0, then the temperature is positive and value (DegC) = + (Temperature value)
- If the Temperature value MSByte bit D11 = 1, then the temperature is negative and value (DegC) = (2's complement of Temperature value)

Table 6-7 shows some examples of 8-bit binary temperature value:

Table 6-7: Example of 8-bit binary temperature settings for temperature ranges

8-bit binary (2's complement)	Hexadecimal Value	TR Value [DegC]
0111 1111	7F	12B
0110 0100	64	100
0101 0000	50	80
0100 1011	4B	75
0011 0010	32	50
0001 1001	19	25
0000 0000	00	0
1111 1111	FF	-1
1110 0111	E7	-25
1100 1001	C9	-55

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6.9 Waveform Setting searching mechanism

As mentioned in Section 6.7, the SSD1685 OTP can store waveform setting and temperature range. If waveform setting and temperature range are programmed in OTP memory, corresponding waveform LUT can be selected according to the sensed temperature to drive the display. The Waveform Setting searching mechanism by driver IC is as follows.

- 1) Read temperature value by command register in the format of 8-bit binary.
- 2) According to read temperature and display mode selection, search LUT in OTP from TR0 to TR23 in sequence. The last match will be selected, then, the corresponding WS will be loaded in the LUT register to drive the display.

Remark: Waveform LUT selection criteria is "Lower temperature bound < Sensed temperature ≤ Upper temperature bound".

Table 6-8 shows an example for the waveform LUT searching from OTP:

- If the read temperature is 25degC, then, WS4 will be selected.
- If the read temperature is 34degC, then, WS7 will be selected. Although 34degC is also in the temperature range TR6, according to searching mechanism, the last match should be selected. Therefore, WS7 is selected.

Waveform TR Lower Limit TR Upper Limit Temperature range in OTP **Temperature LUT in OTP** Range in OTP [Hex] [Hex] WS0 TR0 80 05 -128 DegC < Temperature ≤ 5 DegC WS1 TR1 05 0A 5 DegC < Temperature ≤ 10DegC TR2 0A 0F 10 DegC < Temperature ≤ 15DegC WS2 WS3 TR3 0F 14 15 DegC < Temperature ≤ 20DegC WS4 TR4 14 19 20 DegC < Temperature ≤ 25DegC 25 DegC < Temperature ≤ 30DegC WS5 TR5 19 1E 23 WS6 TR6 1E 30 DegC < Temperature ≤ 35DegC WS7 TR7 21 7F 33 DegC < Temperature ≤ 127DegC 00 00 Others Others

Table 6-8: Example of waveform settings selection based on temperature ranges.

Precaution:

Please ensure the temperature range covers whole range of application temperatures, display will not be updated if no suitable temperature range matches the sensed temperature.

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6.10 One Time Programmable (OTP) Memory

In the SSD1685, there is an embedded OTP memory which is designed to store the waveform settings of different temperature range and some variables/parameters. The OTP memory can store 24 sets of waveform LUT settings (WS), 24 sets of temperature range (TR), VCOM value, display mode selection, waveform version and user ID. Figure 6 7 shows the address mapping of the 24 waveform setting (WS0 to WS23) and temperature range (TR0 to TR23).

0 232 233 WS1 233 WS1 465 466 WS2 698 699 WS3 931 932 WS4 1164 WS2 5558 5591 WS2 55595 5594 TR1 5596 TR2 5598 5599 5600 TR4 TR3 5600 TR4 TR3 5600 TR4 TR2 5636 5637 5638 5639 TR23 5639 TR23 5639 TR23 5639 TR23 5639 TR23 5639 TR25 5636 TR22 5636 TR22 5636 TR22 5637 5638 5639 TR23	addr.	D7	D6	D5	D4	D3	D2	D1	D0
232 233	0								
233 465 466 WS2 698 699 WS3 931 932 1164 1164 5126 WS22 5358 5359 WS23 5591 5592 TR0 5594 TR1 5595 5596 TR2 5596 TR2 5599 TR3 5600 TR4 TR2 5636 5637 TR22					W	S0			
WS1 465 W66 WS2 698 699 WS3 931 932 WS4 1164 5126 WS22 5358 5591 WS23 5592 TR0 5593 TR1 5594 TR1 5595 TR2 5597 TR2 5598 TR3 5600 TR4 5636 TR22 5637 TR22									
465 466 466 898 699 931 932 1164 1164 5126 8WS2 5358 5359 5591 5592 5593 5594 5594 5595 5596 5597 5598 5598 5599 5600 TR4 5636 5637 TR22 5638	233								
466 WS2 698 699 WS3 931 932 WS4 1164 5126 WS22 5358 5359 5591 WS23 5592 TR0 5593 TR1 5594 TR1 5595 TR2 5598 TR3 5600 TR4 5636 TR22 5638 TR22					W	S1			
WS2									
698 699 WS3 931 932 WS4 1164 5126 WS22 5358 5359 WS23 5591 TR0 5592 5593 TR0 5594 5594 TR1 5596 5597 5598 5599 TR2 5636 TR3 TR3 5636 TR4 TR22	466								
699 931 932 1164 5126 5358 5359 W\$22 5591 5592 5593 5594 5594 5595 5596 5597 5598 5599 TR2 5598 5599 TR3 5636 TR4 TR22 5636 TR22					VV	52			
WS3 931 WS4 1164 5126 WS22 5358 S359 WS23 5591 TR0 5592 TR0 5593 TR1 5594 TR1 5595 TR2 5597 TR3 5598 TR3 5600 TR4 5636 TR22 5637 TR22									
931 932 1164 5126 5358 5359 WS22 5591 5592 5593 5594 5594 5595 5596 5597 5598 5598 5599 5600 TR2 TR3 5636 5637 TR22 5638 TR22									
932 1164 1164 5126 5358 5359 5591 5592 5593 5594 5594 5595 TR1 5595 TR2 5596 5597 5598 5600 TR4 TR3 5636 TR22 5637 TR22					VV	53			
WS4 1164									
1164 5126 5358 5359 WS23 5591 5592 5593 5594 5594 5595 5596 5597 5598 5599 TR2 TR3 5636 5637 TR22 5638		l			147	24			
5126 5358 5359 WS23 5591 S592 S593 TR0 TR1 S595 S596 S596 TR2 S597 S598 TR3 S600 TR4 TR4 TR2 TR3 TR3 TR3 TR3 TR4 TR2 TR3					VV	54			
5126 S5358 5359 WS23 5591 5592 5593 5593 5594 TR0 5595 5596 5597 5598 TR2 5598 5599 TR3 5600 TR4 TR4 5636 TR22 5637 TR22	1164								
5126 S5358 5359 WS23 5591 5592 5593 5593 5594 TR0 5595 5596 5597 5598 TR2 5598 5599 TR3 5600 TR4 TR4 5636 TR22 5637 TR22									
WS22 5358 5359 WS23 5591 5592 5593 5594 5595 5596 5596 5597 5598 TR2 5599 5600 5601 TR4 TR2 5636 TR22 5637 TR22					•	•			
WS22 5358 5359 WS23 5591 5592 5593 5594 5595 5596 5596 5597 5598 TR2 5599 5600 5601 TR4 TR2 5636 TR22 5637 TR22	5126								
5358 5359 WS23 5591 TR0 5592 TR0 5593 TR1 5594 TR1 5595 TR2 5597 TR3 5598 TR3 5600 TR4 5636 TR22 5637 TR22 5638 TR22					w	322			
5359 5591 S592 TR0 S593 TR1 S595 S596 S596 TR2 S597 S598 TR3 S600 TR4 TR4 TR4 TR2 TR3 TR4 TR2 TR3 TR4 TR4 TR2 TR3 TR4 TR4 TR4 TR2 TR3 TR3 TR3 TR4 TR4 TR4 TR2 TR3					•••	,			
WS23 5591 5592 5593 5594 5595 5596 5596 5597 5598 5599 TR3 5600 5601 TR4 TR22 5636 TR22									
5591 5592 5593 5593 TR0 5594 5595 5596 5597 5598 5599 TR3 5599 TR3 5600 TR4		i			WS	323			
5593 5594 5595 5596 5596 5597 TR2 5598 5599 5600 TR4 5636 5637 TR22		1							
5593 5594 5595 5596 5597 5598 5599 5600 5601 TR4 TR2 5636 5637	5592					20			
5595 5596 5597 5598 5599 TR3 5600 5601 TR4 5636 TR22 5637 TR22	5593	1			11	10			
5595 5596 5597 5598 5599 5600 5601 TR4 5636 5637 TR22					ТІ	21			
5597 5598 5599 5600 5601 TR4 5636 5637 TR22									
5597 5598 5599 5600 5601 TR4 5636 5637 TR22				·	TF	32			
5599 5600 TR4 5636 5637 TR22									
5690 5600 5601 TR4 5636 5637 TR22		l			TF	3			
5601 In4 5636 TR22 5638 TR22									
5636 TR22 5637 TR22		l			TF	R4			
5636 TR22 5637 TR22	1000								
5637 5638 TD22		l							
5637 5638 TD22	5636								
5638 TD22		1			TF	22			
5639						00			
	5639	1			II-	23			

Figure 6-7: The Waveform setting mapping in OTP for waveform setting and temperature range

6.11 The Format for Temperature Range (TR)

The format of TR Lower limit and Upper limit as shown in Figure 6-8 which temp_L[7:0] is the lower limit and temp_H[7:0] is the upper limit of the temperature range. There has 24sets of TR for waveform LUT searching.

D7	D6	D5	D4	D3	D2	D1	D0			
	temp_L[7:0]									
	temp_H[7:0]									

Figure 6-8: Format of Temperature Range (TR) in OTP

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6.12 Cascade Mode

The SSD1685 has a cascade mode that can cascade 2 chips to achieve the display resolution up to 432 (sources) x 384 (gates). The pin M/S# is used to configure the chip. When M/S# is connected to VDDIO, the chip is configured as a master chip. When M/S# is connected to VSS, the chip is configured as a slave chip.

When the chip is configured as a master chip, it will be the same as a single chip application, ie, all circuit blocks will be worked as usual. When the chip is configured as a slave chip, its oscillator and booster & regulator circuit will be disabled. The oscillator clock and all booster voltages will be come from the master chip. Therefore, the corresponding pins including CL, VDD, VGH, VGL, VSH1, VSH2, VSL, VGL and VCOM must be connected to the master chip.

6.13 VCI Detection

The VCI detection function is used to detect the VCI level when it is lower than Vlow, threshold voltage set by register.

In SSD1685, there is a command to execute the VCI detection function. When the VCI detection command is issued, the VCI detection will be executed. During the detection period, BUSY output is at high level. BUSY output is at low level when the detection is completed. Then, user can issue the Status Bit Read command to check the status bit for the result of VCI, which 0 is normal, 1 is VCI<Vlow.

6.14 HV Ready Detection

The HV Ready detection function is used to detect whether the analog block is ready.

In SSD1685, there is a command to execute the HV Ready detection function. When the HV Ready detection command is issued, the HV Ready will be executed. During the detection period, BUSY output is at high level. BUSY output is at low level when the detection is completed. Then, user can issue the Status Bit Read command to check the status bit for the result of HV Ready, which 0 is normal, 1 indicate HV is not ready.

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7 COMMAND TABLE

Table 7-1: Command Table

0 0 0 1 0 1	0 01 1 1 1 1	0 A ₇ 0 0	0 A ₆ 0 0	0 A ₅ 0	0 A ₄ 0	0 A ₃ 0	0 A ₂ 0 B ₂	0 A ₁ 0 B ₁	1 A ₀ A ₈ B ₀	Driver Output control	Gate setti A[8:0]= 17 MUX Gate B [2:0] = 0 Gate scan	ng 'Fh [POR] e lines set	ting as (A	
0 1	1	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	Driver Output control	A[8:0]= 17 MUX Gate B [2:0] = 0	7Fh [POR] e lines set 000 [POR]	ting as (A	
0 1	1	0	0	0	0	0	0	0	A 8		MUX Gate B [2:0] = 0	e lines set	ting as (A	
	_	_									B [2:0] = 0)00 [POR]		[8:0] + 1).
0 1	1	0	0	0	0	0	B ₂	B ₁	B ₀				 .	
											B[2]: GD Selects th GD=0 [PC G0 is the output sec GD=1, G1 is the output sec B[1]: SM Change si SM=0 [PC G0, G1, Gi right gate SM=1, G0, G2, G B[0]: TB	e 1st outp DR], 1st gate of quence is 1st gate of quence is canning of DR], 62, G3G interlaced	out Gate output cha G0, G1, C output cha G1, G0, C rder of ga G382, G38 d) 2, G1, G3	nnel, gate 33, G2, te driver. 3 (left and
											TB = 0 [P0 TB = 1, so			
0 0	0 03	0	0	0	0	0	0	1	1	Gate Driving voltage	Set Gate	drivina vo	Itage	
	1	0	0	0	A ₄	A ₃	A ₂	A ₁	A ₀	Control	A[4:0] = 0		itago	
	•			Ĭ	, 14	7.5	, , ,	, , ,	7.0		VGH setti			
											A[4:0]	VGH	A[4:0]	VGH
											00h	20	0Dh	15
											03h	10	0Eh	15.5
											04h	10.5 11	0Fh	16
											05h		10h	16.5
											06h 07h	11.5 12	11h 12h	17 17.5
											07H	12.5	13h	18
											07h	12.5	14h	18.5
											07H 08h	12.5	15h	19
											09h	13	16h	19.5
											09H	13.5	17h	20
											0Bh	14	Other	NA
											0Ch	14.5	Other	14/1
											0011	17.0		
	1	1		l										

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Com	Command Table											
R/W#	D/C#	Hex	D 7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	04	0	0	0	0	0	1	0	0	Source Driving voltage	Set Source driving voltage
0	1		A ₇	A 6	A 5	A ₄	A ₃	A_2	A ₁	A_0	Control	A[7:0] = 41h [POR], VSH1 at 15V
0	1		B ₇	B ₆	B ₅	B ₄	Вз	B ₂	B ₁	B ₀		B [7:0] = A8h [POR], VSH2 at 5V. C[7:0] = 32h [POR], VSL at -15V
0	1		C ₇	C ₆	C 5	C ₄	Сз	C ₂	C ₁	C ₀		Remark: VSH1>=VSH2

B[7] = 1,

VSH2 voltage setting from 2.4V to 8.6V

A/B[7:0]	VSH1/VSH2	A/B[7:0]	VSH1/VSH2		
8Eh	2.4	AEh	5.6		
8Fh	2.5	AFh	5.7		
90h	2.6	B0h	5.8		
91h	2.7	B1h	5.9		
92h	2.8	B2h	6		
93h	2.9	B3h	6.1		
94h	3	B4h	6.2		
95h	3.1	B5h	6.3		
96h	3.2	B6h	6.4		
97h	3.3	B7h	6.5		
98h	3.4	B8h	6.6		
99h	3.5	B9h	6.7		
9Ah	3.6	BAh	6.8		
9Bh	3.7	BBh	6.9		
9Ch	3.8	BCh	7		
9Dh	3.9	BDh	7.1		
9Eh	4	BEh	7.2		
9Fh	4.1	BFh	7.3		
A0h	4.2	C0h 7.4			
A1h	4.3	C1h 7.5			
A2h	4.4	C2h	7.6		
A3h	4.5	C3h	7.7		
A4h	4.6	C4h	7.8		
A5h	4.7	C5h	7.9		
A6h	4.8	C6h	8		
A7h	4.9	C7h	8.1		
A8h	5	C8h	8.2		
A9h	5.1	C9h	8.3		
AAh	5.2	CAh	8.4		
ABh	5.3	CBh	8.5		
ACh	5.4	CCh	8.6		
ADh	5.5	Other	NA		

A[7]/B[7] = 0,

VSH1/VSH2 voltage setting from 8.8V to 17V

A/B[7:0]	VSH1/VSH2	A/B[7:0]	VSH1/VSH2
21h	8.8	37h	13
23h	9	38h	13.2
24h	9.2	39h	13.4
25h	9.4	3Ah	13.6
26h	9.6	3Bh	13.8
27h	9.8	3Ch	14
28h	10	3Dh	14.2
29h	10.2	3Eh	14.4
2Ah	10.4	3Fh	14.6
2Bh	10.6	40h	14.8
2Ch	10.8	41h	15
2Dh	11	42h	15.2
2Eh	11.2	43h	15.4
2Fh	11.4	44h	15.6
30h	11.6	45h	15.8
31h	11.8	46h	16
32h	12	47h	16.2
33h	12.2	48h	16.4
34h	12.4	49h	16.6
35h	12.6	4Ah	16.8
36h	12.8	4Bh	17
-		Other	NA

C[7] = 0, VSL setting from -5V to -17V

C[7:0]	VSL
0Ah	-5
0Ch	-5.5
0Eh	-6
10h	-6.5
12h	-7
14h	-7.5
16h	-8
18h	-8.5
1Ah	-9
1Ch	-9.5
1Eh	-10
20h	-10.5
22h	-11
24h	-11.5
26h	-12
28h	-12.5
2Ah	-13
2Ch	-13.5
2Eh	-14
30h	-14.5
32h	-15
34h	-15.5
36h	-16
38h	-16.5
3Ah	-17
Other	NA

0	0	80	0	0	0	0	1	0	0		Initial Code Setting OTP Program	Program Initial Code Setting
												The command required CLKEN=1.
												Refer to Register 0x22 for detail.
												BUSY pad will output high during
												operation.
				•								
0	0	09	0	0	0	0	1	0	0	1		Write Register for Initial Code Setting
0	1		A ₇	A 6	A 5	A ₄	A ₃	A ₂	A ₁	A ₀		Selection
0	1		B ₇	B ₆	B ₅	B ₄	Вз	B ₂	Bı	B ₀		A[7:0] ~ D[7:0]: Reserved
U	ı		D 7	D 6	D 5	D 4	D 3	D 2	D1	D 0		Details refer to Application Notes of Initial
0	1		C ₇	C_6	C ₅	C ₄	C ₃	C_2	C_1	C_0		Code Setting
0	1		D_7	D_6	D_5	D_4	D ₃	D_2	D_1	D ₀		

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New Dice Hex Dice Di	Com	man	d Tal	ole										
O	R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description	
O	0	0	0A	0	0	0	0	1	0	1	0	Read Register for Initial	-	r for Initial Code Setting
O														
O	0	0	OC.	Λ	0	Λ	Λ	1	1	Λ	Λ	Rooster Soft start	Booster Enable	with Phase 1. Phase 2 and Phase 3
1	-		00											
Section Sect													A[7:0] -> Soft sta	art setting for Phase1
1													= 8Bh	[POR]
O(1,0) O													= 9Ch	[POR]
D[7:0] - Duration setting	U	'		U	U	D 5	D4	D 3	D2	D ₁	D ₀		C[7:0] -> Soft sta	art setting for Phase3
Bit(6.4) Bit(6.4) Driving Strength Selection													D[7:0] -> Duratio	n setting
Selection O000 1(Weakest)													Bit Descrip A[6:0] / B[6	i:0] / C[6:0]:
000													Bit[6:4]	
001 2 010 3 011 4 100 5 101 6 110 7 111 8(Strongest)													000	
011													001	2
100 5 101 6 110 7 1111 8(Strongest)													010	3
101 6 110 7 111 8(Strongest)													011	4
110													100	5
Bit[3:0] Min Off Time Setting of GDR (Time unit 0000													101	6
Bit[3:0] Min Off Time Setting of GDR Time unit 0000													l	
Display Time unit													111	8(Strongest)
NA														
0011 0100 2.6 0101 3.2 0110 3.9 0111 4.6 1000 5.4 1001 6.3 1010 7.3 1011 8.4 1100 9.8 1101 11.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 1111 16.5 1110 13.8 13.2 13														NA
0101 3.2 0110 3.9 0111 4.6 1000 5.4 1001 6.3 1010 7.3 1011 8.4 1100 9.8 1101 11.5 1110 13.8 1111 16.5 D[5:0]: duration setting of phase o														
0110 3.9 0111 4.6 1000 5.4 1001 6.3 1010 7.3 1011 8.4 1100 9.8 1101 11.5 1110 13.8 1111 16.5 1111														
0111														
1000 5.4 1001 6.3 1010 7.3 1011 8.4 1100 9.8 1101 11.5 1101 13.8 1111 16.5 1111 16.5 1111 16.5 1111 16.5 16.5 17.5														
1001 6.3 1010 7.3 1011 8.4 1100 9.8 1101 11.5 1110 13.8 1111 16.5 1111														
1010 7.3 1011 8.4 1100 9.8 1101 11.5 1110 13.8 1111 16.5 111													-	
1011														
1101														
1110													1100	9.8
1111 16.5													1101	11.5
D[5:0]: duration setting of phase D[5:4]: duration setting of phase 3 D[3:2]: duration setting of phase 2 D[1:0]: duration setting of phase 1 Bit[1:0] Duration of Phase [Approximation] 00 10ms 01 20ms 10 30ms													1110	13.8
D[5:4]: duration setting of phase 3 D[3:2]: duration setting of phase 2 D[1:0]: duration setting of phase 1 Bit[1:0] Duration of Phase [Approximation] 00 10ms 01 20ms 10 30ms													1111	16.5
01 20ms 10 30ms													D[5:4]: du D[3:2]: du D[1:0]: du	ration setting of phase 3 ration setting of phase 2 ration setting of phase 1 Duration of Phase
10 30ms													00	10ms
													01	20ms
													11	40ms

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Com	man	d Ta	ble									
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
							1					
0	1	10	0	0	0	0	0	0	0 A ₁	0 A ₀	Deep Sleep mode	Deep Sleep mode Control: A[1:0]: Description 00 Normal Mode [POR] 01 Enter Deep Sleep Mode 1 11 Enter Deep Sleep Mode 2 After this command initiated, the chip will enter Deep Sleep Mode, BUSY pad will
												keep output high. Remark: To Exit Deep Sleep mode, User required to send HWRESET to the driver
0	0	11	0	0	0	1	0	0	0	1	Data Entry mode setting	Define data entry sequence
0	1	1	0	0	0	0	0	A ₂	A ₁	Ao	Data Entry mode Setting	A[2:0] = 011 [POR] A [1:0] = ID[1:0] Address automatic increment / decrement setting The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. 00 —Y decrement, X decrement, 01 —Y decrement, X increment, 10 —Y increment, X increment, 11 —Y increment, X increment [POR] A[2] = AM Set the direction in which the address counter is updated automatically after data are written to the RAM. AM= 0, the address counter is updated in the X direction. [POR] AM = 1, the address counter is updated in the Y direction.
0	0	12	0	0	0	1	0	0	1	0	SW RESET	It resets the commands and parameters to their S/W Reset default values except R10h-Deep Sleep Mode During operation, BUSY pad will output high. Note: RAM data are unaffected by this command.

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Com	ommand Table W# D/C# Hex D7 D6 D5 D4 D3 D2 D1 D0 Command Description													
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description		
0	0	14	0	0	0	1	0	1	0	0	HV Ready Detection	HV ready detection A[7:0] = 00h [POR] The command required CLKEN=1 and ANALOGEN=1. Refer to Register 0x22 for detail. After this command initiated, HV Ready detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F). A[6:4]=n for cool down duration: 10ms x (n+1)		
0	1		0	A ₆	A ₅	A ₄	0	A ₂	A ₁	A ₀		A[6:4]=n for cool down duration:		
0	0	15	0	0	0	1	0	1	0	1	VCI Detection	VCI Detection		
0	1		0	0	0	0	0	A ₂	A1	Ao		A[2:0] = 100 [POR] , Detect level at 2.3V A[2:0] : VCI level Detect A[2:0] VCI level 011 2.2V 100 2.3V 101 2.4V 110 2.5V 111 2.6V Other NA The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. After this command initiated, VCI detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F).		
	_	10	_	_	_	4	4	_	^		Tomporatura Caraca	Tomporatura Canaar Calastica		
0	1	18	0 A ₇	0 A ₆	A 5	1 A ₄	1 A ₃	0 A ₂	0 A ₁	0 A ₀	Temperature Sensor Control	Temperature Sensor Selection A[7:0] = 48h [POR], external temperatrure sensor A[7:0] = 80h Internal temperature sensor		
0	0	1A	0	0	0	1	1	0	1	0	Temperature Sensor	Write to temperature register.		
0	1	- •	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	Control (Write to temperature register)	A[7:0] = 7Fh [POR]		
0	0	1B	0	0	0	1	1	0	1	1	Temperature Sensor	Read from temperature register.		
1	1	טו	A ₇	A ₆	A 5	л А ₄	A ₃	A ₂	A ₁	A ₀	Temperature Sensor Control (Read from	nteau nom temperature register.		
'	1		Λ/	76	7 .5	/ 14	/ 13	<i>1</i> 72	~ 1	70	temperature register)			
<u></u>														

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Com	Command Table													
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description		
0	0	1C	0	0	0	1	1	1	0	0	Temperature Sensor	Write Command to External temperature		
0	1		A_7	A_6	A 5	A_4	A ₃	A_2	A ₁	A_0	Control (Write Command	sensor.		
0	1		B ₇	B ₆	B ₅	B ₄	Вз	B ₂	B ₁	B ₀	to External temperature sensor)	A[7:0] = 00h [POR], B[7:0] = 00h [POR],		
0	1		C ₇	C ₆	C ₅	C ₄	Сз	C ₂	C ₁	Co	Sensor)	C[7:0] = 0011[FOR], C[7:0] = 00h[FOR],		
												A[7:6] A[7:6] Select no of byte to be sent 00 Address + pointer 01 Address + pointer + 1st parameter 10 Address + pointer + 1st parameter + 2nd pointer 11 Address A[5:0] - Pointer Setting B[7:0] - 1st parameter C[7:0] - 2nd parameter The command required CLKEN=1. Refer to Register 0x22 for detail. After this command initiated, Write Command to external temperature sensor starts. BUSY pad will output high during operation.		
0	0	20	0	0	1	0	0	0	0	0	Master Activation	Activate Display Update Sequence The Display Update Sequence Option is located at R22h. BUSY pad will output high during operation. User should not interrupt this operation to avoid corruption of panel images.		
0 0	1 1	21	O	A6 B6	A ₅	O A4 O	A ₃	A ₂	O A1 O	A ₀ 0	Display Update Control	RAM content option for Display Update A[7:0] = 00h [POR] B[7:0] = 00h [POR] A[7:4] Red RAM option 0000 Normal 0100 Bypass RAM content as 0 1000 Inverse RAM content A[3:0] BW RAM option 0000 Normal 0100 Bypass RAM content as 0 1000 Inverse RAM content as 0 1000 Inverse RAM content B[7:6] Resolution select 00 Display resolution is 200x384 01 Display resolution is 184x384		
												10 Display resolution is 168x384 11 Display resolution is 216x384		

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Com	man	d Ta	ble										
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description	
0	0	22	0	0	1	0	0	0	1	0	Display Update	Display Update Sequence Option	
0	1		A_7	A_6	A_5	A_4	A 3	A_2	A_1	A_0	Control 2	Enable the stage for Master Act	tivation
												A[7:0]= FFh (POR)	Parameter
												Operating sequence	(in Hex)
												Enable clock signal	80
												Disable clock signal	01
												Enable clock signal → Enable Analog	C0
												Disable Analog	00
												→ Disable clock signal	03
												Enable clock signal → Load LUT with DISPLAY Mode 1	91
												→ Disable clock signal	
												Enable clock signal → Load LUT with DISPLAY Mode 2 → Disable clock signal	99
												Enable clock signal → Load temperature value → Load LUT with DISPLAY Mode 1 → Disable clock signal	B1
												Enable clock signal → Load temperature value → Load LUT with DISPLAY Mode 2 → Disable clock signal	В9
												Enable clock signal → Enable Analog → Display with DISPLAY Mode 1 → Disable Analog → Disable OSC	C7
												Enable clock signal → Enable Analog → Display with DISPLAY Mode 2 → Disable Analog → Disable OSC	CF
												Enable clock signal → Enable Analog → Load temperature value → DISPLAY with DISPLAY Mode 1 → Disable Analog → Disable OSC	F7
												Enable clock signal → Enable Analog → Load temperature value → DISPLAY with DISPLAY Mode 2 → Disable Analog → Disable OSC	FF
_		0.4	^		4	^	_	4	0	0	Make DAM (Dissis Missis)	After this compared data and the	م بینال او م
0	0	24	0	0	1	0	0	1	0	0	Write RAM (Black White) / RAM 0x24	After this command, data entrie written into the BW RAM until a command is written. Address pondivance accordingly	nother
												For Write pixel: Content of Write RAM(BW) = For Black pixel: Content of Write RAM(BW) = 0	

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Com	man	d Ta	ble									
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	26	0	0	1	0	0	1	1	0	Write RAM (RED) / RAM 0x26	After this command, data entries will be written into the RED RAM until another command is written. Address pointers will advance accordingly. For Red pixel: Content of Write RAM(RED) = 1 For non-Red pixel [Black or White]: Content of Write RAM(RED) = 0
												Content of Write RAIVI(RED) = 0
0	0	27	0	0	1	0	0	1	1	1	Read RAM	After this command, data read on the MCU bus will fetch data from RAM. According to parameter of Register 41h to select reading RAM0x24/ RAM0x26, until another command is written. Address pointers will advance accordingly.
-												The 1 st byte of data read is dummy data.
0	0	28	0	0	1	0	1	0	0	0	VCOM Sense	Enter VCOM sensing conditions and hold for duration defined in 29h before reading VCOM value. The sensed VCOM voltage is stored in register The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail.
												BUSY pad will output high during operation.
0	0	29	0	0	1	0	1	0	0	1	VCOM Sense Duration	Stabling time between entering VCOM
0	1		0	1	0	0	A 3	A 2	A ₁	A ₀		sensing mode and reading acquired. A[3:0] = 9h, duration = 10s. VCOM sense duration = (A[3:0]+1) sec
0	0	2A	0	0	1	0	1	0	1	0	Program VCOM OTP	Program VCOM register into OTP
ŭ)	27 ())	•	•	•	•	•	Ü	r rogram v oom om	The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.

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Com	man	d Tal	ble												
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Descript	tion		
0	0	2C	0	0	1	0	1	1	0	0	Write VCOM register	Write VC	OM registe	er from M	ICU interface
0	1	-	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	-	A[7:0] =	00h [POR]		
												A[7:0]	VCOM	A[7:0]	VCOM
												08h	-0.2	44h	-1.7
												0Ch	-0.3	48h	-1.8
												10h	-0.4	4Ch	-1.9
												14h	-0.5	50h	-2
												18h	-0.6	54h	-2.1
												1Ch	-0.7	58h	-2.2
												20h	-0.8	5Ch	-2.3
												24h	-0.9	60h	-2.4
												28h	-1	64h	-2.5
												2Ch	-1.1	68h	-2.6
												30h	-1.2	6Ch	-2.7
												34h	-1.3	70h	-2.8
												38h 3Ch	-1.4 -1.5	74h 78h	-2.9 -3
												40h	-1.5 -1.6	Other	NA
												4011	-1.0	Other	INA
0	0	2D	0	0	1	0	1	1	0	1	OTP Register Read for	Read R	egister for	Display (Option:
1	1		A ₇	A 6	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	Display Option				
1	1		B ₇	B ₆	B ₅	B ₄	Вз	B ₂	B ₁	B ₀			VCOM OTI		on
1	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀		(Comm	and 0x37,	Byte A)	
1	1		D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀		B[7:0]:	VCOM Reg	ister	
1	1		E ₇	E ₆	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀			and 0x2C)	,	
1	1		F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	F ₀		017.01	O(7 01 D)		
1	1		G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G₀			G[7:0]: Dis and 0x37,		
1	1		H ₇	H ₆	H ₅	H ₄	H ₃	H ₂	H ₁	H ₀		[5 bytes		Dyte D to	Dyte ()
1	1			I ₆	I ₅	I ₄	I ₃	I ₁₂		I ₀			-		
1	1		Ι ₇		J ₅				l ₁				K[7:0]: Wa		
	1			J ₆		J ₄	J ₃	J ₂	J ₁	J ₀		[4 bytes	and 0x37,	Byte G to	Byte J)
1	ı		K_7	K ₆	K ₅	K ₄	K ₃	K_2	K ₁	K ₀		[4 Dytes	9]		
0	0	2E	0	0	1	0	1	1	1	0	User ID Read		Byte User		
1	1		A ₇	A ₆	A 5	A ₄	A ₃	A ₂	A ₁	A ₀					8, Byte A and
1	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀		Byte AD) [30 bytes]	
1	1		C ₇	C ₆	C ₅	C ₄	Сз	C ₂	C ₁	Co					
							l .			i i					
1	1						:								
1	1		Z_7	Z_6	Z_5	Z_4	Z_3	Z_2	Z ₁	Z ₀					
1	1		$\overline{AA_7}$	AA_6	AA_5	$\overline{AA_4}$	AA_3	\overline{AA}_2	AA_1	AA_0					
1	1		AB ₇	AB ₆	AB ₅	AB ₄	AB ₃	AB ₂	AB ₁	AB ₀					
1	1						АСз								
1	1						AD ₃								
											Otatus Dir Dunid	D	24.4	DOD 2. 1	241
0	0	2F	0	0	1	0	1	1	1	1	Status Bit Read	Read IC	status Bit [POR 0x0)1]

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	man		ble									
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
1	1		0	0	A 5	A4	0	0	A ₁	Ao		A[5]: HV Ready Detection flag [POR=0] 0: Ready 1: Not Ready A[4]: VCI Detection flag [POR=0] 0: Normal 1: VCI lower than the Detect level A[3]: [POR=0] A[2]: Busy flag [POR=0] 0: Normal 1: BUSY A[1:0]: Chip ID [POR=01] Remark: A[5] and A[4] status are not valid after RESET, they need to be initiated by command 0x14 and command 0x15 respectively.
											,	
0	0	30	0	0	1	1	0	0	0	0	Program WS OTP	Program OTP of Waveform Setting The contents should be written into RAM before sending this command. The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	31	0	0	1	1	0	0	0	1	Load WS OTP	Load OTP of Waveform Setting
U	O	31	J	J	ı	ı	V	V	U	ı	Load WO OTT	The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
		00	•	•		4					\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	hat is a tall to the same of
0	0	32	0 A ₇	0 A ₆	1 A ₅	1 A ₄	0 A ₃	0 A ₂	1 A ₁	0 A ₀	Write LUT register	Write LUT register from MCU interface [227 bytes], which contains the content of
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	H ₂	B ₁	B ₀		VS[nX-LUTm], TP[nX], RP[n], SR[nXY], FR
0	1		:	:	:	:	:	:	:	:		and XON[nXY] Refer to Session 6.7 WAVEFORM
0	1		•									SETTING
							<u> </u>			<u> </u>		
0	0	34	0	0	1	1	0	1	0	0	CRC calculation	CRC calculation command For details, please refer to SSD1685 application note. BUSY pad will output high during operation.
0	0	35	0	0	1	1	0	1	0	1	CRC Status Read	CRC Status Read
1	1		A ₁₅	A ₁₄	A ₁₃	A ₁₂		A ₁₀	A ₉	A ₈		A[15:0] is the CRC read out value
1	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		
	•				•		•			•	•	

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Com	man	d Ta	ble									
R/W#	D/C#	Hex	D 7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	36	0	0	1	1	0	1	1	0	Program OTP selection	Program OTP Selection according to the OTP Selection Control [R37h and R38h]
												The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
		0.7	_	_			_		_		With Device to Division	With Burling to Black Out of
0	0	37	0	0	1	1	0	1	1	1	Write Register for Display Option	Write Register for Display Option A[7] Spare VCOM OTP selection
0	1		A ₇	0	0	0	0	0	0	0	Option	0: Default [POR]
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀		1: Spare
0	1		D ₇	D ₆	D ₅	D ₄	D ₃	C ₂	D ₁	D ₀		B[7:0] Display Mode for WS[7:0]
0	1		E ₇	E ₆	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀		C[7:0] Display Mode for WS[15:8]
0	1		0	F ₆	0	0	F ₃	F ₂	F ₁	F ₀		D[7:0] Display Mode for WS[23:16] 0: Display Mode 1
0	1		G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀		1: Display Mode 2
0	1		H ₇	H ₆	H ₅	H ₄	H ₃	H ₂	H₁	H ₀		
0	1		I ₇	l ₆	I 5	I 4	l ₃	l ₂	I ₁	I ₀		F[6]: Ping-Pong for Display Mode 2 0: RAM Ping-Pong disable [POR]
0	1		J_7	J ₆	J ₅	J ₄	J ₃	J ₂	J₁	J_0		1: RAM Ping-Pong enable
												G[7:0]~J[7:0] module ID /waveform version.
												Remarks: 1) A[7:0]~J[7:0] can be stored in OTP 2) RAM Ping-Pong function is not support for Display Mode 1
				Т	1	Т	Т	1		1	Γ	
0	1	38	0 A ₇	0 A ₆	1 A ₅	1 A ₄	1 A ₃	0 A ₂	0 A ₁	0 A ₀	Write Register for User ID 	Write Register for User ID A[7:0]]~AD[7:0]: UserID [30 bytes]
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	H ₂	B ₁	B ₀		
0	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁			Remarks: A[7:0]~AD[7:0] can be stored in OTP
0	1											
0	1		Z ₇	Z ₆	Z ₅	Z ₄	Z ₃	Z ₂	Z ₁	Z ₀		
0	1							AA ₂				
0	1							AB ₂				
0	1							AC ₂				
0	1		AD ₇	AD ₆	AD ₅	AD ₄	ADз	AD ₂	AD ₁	AD ₀		
0	0	39	0	0	1	1	1	0	0	1	OTP program mode	OTP program mode
0	1		0	0	0	0	0	0	A ₁	A ₀		A[1:0] = 00: Normal Mode [POR] A[1:0] = 11: Internal generated OTP programming voltage
												Remark: User is required to EXACTLY follow the reference code sequences

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Com	man	d Ta	ble										
R/W#			D7	D6	D5	D4	D3	D2	D1	D0	Command	Description	
0	0	3C	0	0	1	1	1	1	0	0	Border Waveform Control	Select border	r waveform for VBD
0	1		A ₇	A ₆	A ₅	A ₄	0	0	A ₁	A ₀		A[7:0] = C0h	[POR], set VBD as HIZ.
	•		,	, 10	7.5					1.0			ct VBD option
												A[7:6]	Select VBD as
												00	GS Transition,
												01	Defined in A[2] and A[1:0] Fix Level,
												01	Defined in A[5:4]
												10	VCOM
												11[POR]	HiZ
													_
													evel Setting for VBD
												A[5:4]	VBD level
												00 01	VSS VSH1
												10	VSH
												11	VSH2
													ransition setting for VBD
												VBD Level S	
												00b: VCOM ;	01b: VSH1;
												10b: VSL; 11 A[1:0]	VBD Transition
												00	LUT0
												01	LUT1
												10	LUT2
												11	LUT3
					ı		ı	ı		ı	l	1	
0	0	3F	0	0	1	1	1	1	1	1	End Option (EOPT)	Option for LL	JT end
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		Set this byte	to 22h
0	0	41	0	1	0	0	0	0	0	1	Read RAM Option	Read RAM C	
0	1		0	0	0	0	0	0	0	A_0		A[0]= 0 [POF	
												U : Read RAN	M corresponding to RAM0x24 M corresponding to RAM0x26
												I . Nead NAI	w corresponding to HAMOX20
										l .			
0	0	44	0	1	0	0	0	1	0	0	Set RAM X - address	Specify the s	tart/end positions of the
											Start / End position	window addre	ess in the X direction by an
												address unit	for RAM
												A[E.O], VOA[E	Evol Vetort DOD 00h
													5:0], XStart, POR = 00h 5:0], XEnd, POR = 18h
												5[0:0]: 7(2)	3.0], 7.2.10, 1.0.1
0	1		0	0	A 5	A ₄	A 3	A ₂	A ₁	A ₀			
0	1		0	0	B ₅	B ₄	Вз	B ₂	B ₁	B ₀			

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Com	man	d Ta	ble												
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Descripti	on		
0	0	45	0	1	0	0	0	1	0	1	Set Ram Y- address	Specify th	e start/end	d positions	of the
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	Start / End position				tion by an
0	1		0	0	0	0	0	0	0	A 8		address u	nit for RAI	M	
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀		A[8:0]: YS	A[8:0]. YS	Start, POR	= 000h
0	1		0	0	0	0	0	0	0	B ₈	-	B[8:0]: YE			
	1				l	l		l		I.		1			
0	0	46	0	1	0	0	0	1	1	0				M for Reg	ular Pattern
											Regular Pattern	A[7:0] = 0	0h [POR]		
												A[7]: The	1st step v	alue, POR	t = 0
												A[6:4]: Ste	ep Height,	POR= 00	0
													ter RAM ir	Y-direction	on according
												to Gate A[6:4]	Height	A[6:4]	Height
												000	8	100	128
												001	16	101	256
												010	32	110	384
												011	64	111	NA
												V[0.0]* C+	an Midth f	or 160v20	4, POR= 000
															on according
												to Source	.0	. A Gill Goth	on according
												A[2:0]	Width	A[2:0]	Width
												000	8	100	128
												001	16	101	168
												010	32	110	NA
												011	64	111	NA
								l			1	1			

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W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description	on		
0	1		A ₇	A ₆	A ₅	A ₄	0	A ₂	A ₁	A ₀		A[2:0]: Step of alt to Source			
												A[2:0]	Width	A[2:0]	Width
												000	8	100	128
												001	16	101	184
												010	32	110	NA
												011	64	111	NA
												A[2:0]: Step of alt to Source			
												A[2:0]	Width	A[2:0]	Width
												000	8	100	128
												001	16	101	200
												010	32	110	NA
												011	64	111	NA
												A[2:0]: Step of all to Source	er RAM ir		
												A[2:0]	Width	A[2:0]	Width
												000	8	100	128
												001	16	101	216
												010	32	110	NA
												011	64	111	NA
												BUSY pad operation.		ut high du	ring

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Com	man	d Ta	ble												
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Descripti	on		
0	0	47	0	1	0	0	0	1	1	1	Auto Write B/W RAM for	Auto Write	e B/W RAI	M for Regi	ular Pattern
0	1		A ₇	A ₆	A ₅	A ₄	0	A ₂	A ₁	A ₀	Regular Pattern	A[7:0] = 0		J	
												Step of all to Gate	ep Height, ter RAM ir	POR= 00 Y-direction	0 on according
												A[6:4]	Height	A[6:4]	Height
												000	8	100	128
												001	16	101	256
												010	32	110	384
												011	64	111	NA
													ter RAM ir		4, POR= 000 on according
												A[2:0]	Width	A[2:0]	Width
												000	8	100	128
												001	16	101	168
												010	32	110	NA
												011	64	111	NA
													ter RAM ir		4, POR= 000 on according
												A[2:0]	Width	A[2:0]	Width
												000	8	100	128
												001	16	101	184
												010	32	110	NA
												011	64	111	NA
													ter RAM ir		4, POR= 000 on according
												A[2:0]	Width	A[2:0]	Width
												000	8	100	128
												001	16	101	200
												010	32	110	NA
												011	64	111	NA
															4, POR= 000 on according
												A[2:0]	Width	A[2:0]	Width
												000	8	100	128
												001	16	101	216
												010	32	110	NA
												011	64	111	NA
												During op high.	eration, B	USY pad v	will output

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Com	man	d Ta	ble									
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	4E	0	1	0	0	1	1	1		Set RAM X address	Make initial settings for the RAM X address
0	1		0	0	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	counter	in the address counter (AC) A[5:0]: 00h [POR].
0	0	4F	0	1	0	0	1	1	1	1	Set RAM Y address	Make initial settings for the RAM Y address
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0	counter	in the address counter (AC)
0	1		0	0	0	0	0	0	0	A 8		A[8:0]: 000h [POR].
0	0	7F	0	1	1	1	1	1	1	1	NOP	This command is an empty command; it does not have any effect on the display module. However, it can be used to terminate Frame Memory Write or Read Commands.

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8 COMMAND DESCRIPTION

8.1 Driver Output Control (01h)

This triple byte command has multiple configurations and each bit setting is described as follows:

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	MUX7	MUX6	MUX5	MUX4	MUX3	MUX2	MUX1	MUX0
PC	R	0	0	1	0	1	0	1	1
W	1								MUX8
PC)R								1
W	1						GD	SM	TB
PC)R						0	0	0

MUX[8:0]: Specify number of lines for the driver: MUX[8:0] + 1. Multiplex ratio (MUX ratio) from 16 MUX to 384MUX.

GD: Selects the 1st output Gate

This bit is made to match the GATE layout connection on the panel. It defines the first scanning line.

SM: Change scanning order of gate driver.

When SM is set to 0, left and right interlaced is performed.

When SM is set to 1, no splitting odd / even of the GATE signal is performed,

Output pin assignment sequence is shown as below (for 384 MUX ratio):

	SM=0	SM=0	SM=1	SM=1
Driver	GD=0	GD=1	GD=0	GD=1
G0	ROW0	ROW1	ROW0	ROW192
G1	ROW1	ROW0	ROW192	ROW0
G2	ROW2	ROW3	ROW1	ROW193
G3	ROW3	ROW2	ROW193	ROW1
:	:	:	:	:
G190	ROW190	ROW191	ROW95	ROW287
G191	ROW191	ROW190	ROW287	ROW95
G192	ROW192	ROW193	ROW96	ROW288
G193	ROW193	ROW192	ROW288	ROW96
:	:	:	:	:
G380	ROW380	ROW381	ROW190	ROW382
G381	ROW381	ROW380	ROW382	ROW190
G382	ROW382	ROW383	ROW191	ROW383
G383	ROW383	ROW382	ROW383	ROW191

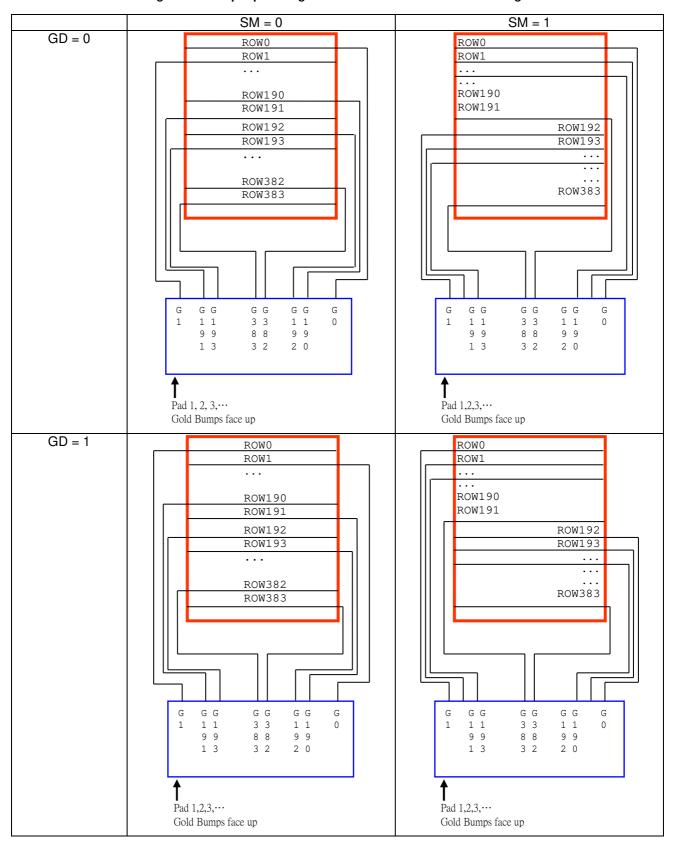
See "Scan Mode Setting" on next page.

TB: Change scanning direction of gate driver.

This bit defines the scanning direction of the gate for flexible layout of signals in module either from up to down (TB = 0) or from bottom to up (TB = 1).

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Figure 8-1: Output pin assignment on different Scan Mode Setting



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8.2 Gate Scan Start Position (0Fh)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	SCN7	SCN6	SCN5	SCN4	SCN3	SCN2	SCN1	SCN0
PC	OR	0	0	0	0	0	0	0	0
W	1	0	0	0	0	0	0	0	SCN8
PC	OR	0	0	0	0	0	0	0	0

This command is to set Gate Start Position for determining the starting gate of display RAM by selecting a value from 0 to 383. Figure 8-2 shows an example using this command of this command when MUX ratio= 384 and MUX ratio= 150 "ROW" means the graphic display data RAM row.

Figure 8-2: Example of Set Display Start Line with no Remapping

[MUX ratio (01h) = 17Fh	MUX ratio (01h) = 0C0h	MUX ratio (01h) = 0C0h
GATE Pin	Gate Start Position (0Fh)	Gate Start Position (0Fh)	Gate Start Position (0Fh)
	= 000h	= 000h	= 05Dh ` ´
G0	ROW0	ROW0	-
G1	ROW1	ROW1	-
G2	ROW2	ROW2	-
G3	ROW3	ROW3	-
:	:	:	:
:	:	:	:
G91	:	:	-
G92	:	:	-
G93	:	:	ROW93
G94	:	:	ROW94
:	:	:	:
:	<u>:</u>	:	:
G190	ROW190	ROW190	:
G191	ROW191	ROW191	:
G192	ROW192	-	:
G193	ROW193	-	:
:	:	:	:
	:	:	:
G284	:	:	ROW284
G285	:	:	ROW285
G286	:	:	-
G287	:	:	-
	:	:	:
:	:	:	:
G380	ROW380	-	-
G381	ROW381	-	-
G382	ROW382	-	-
G383	ROW383	-	-
Display Example	SOLOMON		SOLOMON

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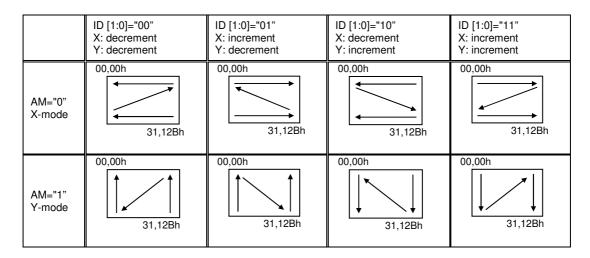
8.3 Data Entry Mode Setting (11h)

This command has multiple configurations and each bit setting is described as follows:

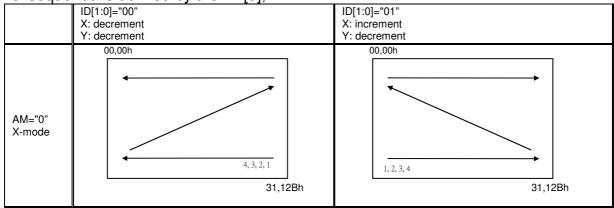
R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1						AM	ID1	ID0
PC)R	0	0	0	0	0	0	1	1

ID[1:0]: The address counter is automatically incremented by 1, after data is written to the RAM when ID[1:0] = "01". The address counter is automatically decremented by 1, after data is written to the RAM when ID[1:0] = "00". The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. The direction of the address when data is written to the RAM is set by AM bits.

AM: Set the direction in which the address counter is updated automatically after data are written to the RAM. When AM = "0", the address counter is updated in the X direction. When AM = "1", the address counter is updated in the Y direction. When window addresses are selected, data are written to the RAM area specified by the window addresses in the manner specified with ID[1:0] and AM bits.



The pixel sequence is defined by the ID [0],



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8.4 Set RAM X - Address Start / End Position (44h)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1			XSA5	XSA4	XSA3	XSA2	XSA1	XSA0
PC)R	0	0	0	0	0	0	0	0
W	1			XEA5	XEA4	XEA3	XEA2	XEA1	XEA0
POR		0	0	1	1	0	0	0	1

XSA[5:0]/XEA[5:0]: Specify the start/end positions of the window address in the X direction by 8 times address unit. Data is written to the RAM within the area determined by the addresses specified by XSA [5:0] and XEA [5:0]. These addresses must be set before the RAM write.

It allows on XEA [5:0] \leq XSA [5:0]. The settings follow the condition on 00h \leq XSA [5:0], XEA [5:0] \leq 31h. The windows is followed by the control setting of Data Entry Setting (R11h)

8.5 Set RAM Y - Address Start / End Position (45h)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	YSA7	YSA6	YSA5	YSA4	YSA3	YSA2	YSA1	YSA0
PC	DR	0	0	0	0	0	0	0	0
W	1	0	0	0	0	0	0	0	YSA8
PC)R	0	0	0	0	0	0	0	0
W	1	YEA7	YEA6	YEA5	YEA4	YEA3	YEA2	YEA1	YEA0
PC	DR	0	0	1	0	1	0	1	1
W	1	0	0	0	0	0	0	0	YEA8
PC)R	0	0	0	0	0	0	0	1

YSA[8:0]/YEA[8:0]: Specify the start/end positions of the window address in the Y direction by an address unit. Data is written to the RAM within the area determined by the addresses specified by YSA [8:0] and YEA [8:0]. These addresses must be set before the RAM write.

It allows YEA [8:0] \leq YSA [8:0]. The settings follow the condition on 00h \leq YSA [8:0], YEA [8:0] \leq 12Bh. The windows is followed by the control setting of Data Entry Setting (R11h)

8.6 Set RAM Address Counter (4Eh-4Fh)

Reg#	R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
4Eh	W	1			XAD5	XAD4	XAD3	XAD2	XAD1	XAD0
	PC	R	0	0	0	0	0	0	0	0
	W	1	YAD7	YAD6	YAD5	YAD4	YAD3	YAD2	YAD1	YAD0
	PC	R	0	0	0	0	0	0	0	0
4Fh	W	1								YAD8
	PC)R								0

XAD[5:0]: Make initial settings for the RAM X address in the address counter (AC). **YAD[8:0]:** Make initial settings for the RAM Y address in the address counter (AC).

After RAM data is written, the address counter is automatically updated according to the settings with AM, ID bits and setting for a new RAM address is not required in the address counter. Therefore, data is written consecutively without setting an address. The address counter is not automatically updated when data is read out from the RAM. RAM address setting cannot be made during the standby mode. The address setting should be made within the area designated with window addresses which is controlled by the Data Entry Setting (R11h) {AM, ID[1:0]}; RAM Address XStart / XEnd Position (R44h) and RAM Address Ystart / Yend Position (R45h). Otherwise undesirable image will be displayed on the Panel.

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9 Absolute Maximum Rating

Table 9-1: Maximum Ratings

Symbol	Parameter	Rating	Unit
Vcı	Logic supply voltage	-0.5 to +6.0	V
VIN	Logic Input voltage	-0.5 to V _{DDIO} +0.5	V
Vout	Logic Output voltage	-0.5 to V _{DDIO} +0.5	V
Topr	Operation temperature range	-40 to +85	°C
T _{STG}	Storage temperature range	-65 to +150	°C

Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description section

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit. For proper operation it is recommended that V_{CI} be constrained to the range $V_{SS} < V_{CI}$. Reliability of operation is enhanced if unused input is connected to an appropriate logic voltage level (e.g., either V_{SS} or V_{DDIO}). Unused outputs must be left open. This device may be light sensitive. Caution should be taken to avoid exposure of this device to any light source during normal operation. This device is not radiation protected.

10 Electrical Characteristics

The following specifications apply for: VSS=0V, VCI=3.0V, VDD=1.8V, T_{OPR}=25^oC.

Table 10-1: DC Characteristics

Symbol	Parameter	Applicable pin	Test Condition	Min.	Тур.	Max.	Unit
Vcı	VCI operation voltage	VCI	-	2.2	3.0	3.7	V
V_{DD}	VDD operation voltage	VDD	-	1.7	1.8	1.9	V
V _{COM_DC}	VCOM_DC output voltage	VCOM	-	-3.0	-	-0.2	V
dV _{COM_DC}	VCOM_DC output voltage deviation	VCOM	-	-200	-	200	mV
V _{СОМ_АС}	VCOM_AC output voltage	VCOM	-	V _{SL} + V _{COM_DC}	V _{СОМ_DС}	V _{SH1+} V _{COM_DC}	٧
V _{GATE}	Gate output voltage	G0~G299	-	-20	-	+20	V
V _{GATE(p-p)}	Gate output peak to peak voltage	G0~G299	-	-	-	40	V
V _{SH1} Positive Source output voltage		VSH1	-	+8.8	+15	+17	V
dV _{SH1}	VSH1 output voltage deviation	VSH1	From 8.8V to 17V	-200	-	200	mV
V _{SH2}	Positive Source output voltage	VSH2	-	+2.4	+5	+17	V
dV _{SH2}	VSH2 output voltage	VSH2	From 2.4V to 8.6V	-100	-	100	mV
	deviation		From 8.8V to 17V	-200	-	200	mV
V _{SL}	Negative Source output voltage	VSL	-	-17	-15	-8.6	V
dV _{SL}	VSL output voltage deviation	VSL	-	-200	-	200	mV
ViH	High level input voltage	SDA, SCL, CS#, D/C#, RES#, BS1,	-	0.8V _{DDIO}	-	-	V
VIL	Low level input voltage	M/S#, CL	-	-	-	0.2V _{DDIO}	V
V _{OH}	High level output voltage	SDA, BUSY, CL	IOH = -100uA	0.9V _{DDIO}	-	-	V
Vol	Low level output voltage		IOL = 100uA	-	-	0.1V _{DDIO}	V
V_{PP}	OTP Program voltage	VPP	-	7.25	7.5	7.75	V

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Symbol	Parameter	Applicable pin	Test Condition	Min.	Тур.	Max.	Unit
Islp_VCI	Sleep mode current	VCI	DC/DC offNo clockNo output loadMCU interface accessRAM data access	-	TBD	TBD	uA
ldslp_VCI1	Current of deep sleep mode 1	VCI	- DC/DC off - No clock - No output load - No MCU interface access - Retain RAM data but cannot access the RAM	-	TBD	TBD	uA
ldslp_VCl2	Current of deep sleep mode 2	VCI	- DC/DC off - No clock - No output load - No MCU interface access - Cannot retain RAM data	-	TBD	TBD	uA
lopr_VCI	Operating Mode current	VCI	VCI=3.0V	-	TBD	-	uA
V _{GH}	Operating Mode Output Voltage	VGH	Enable Clock and Analog by Master Activation Command	19.5	20	20.5	V
V _{SH1}		VSH1	VGH=20V VGL=-VGH	14.8	15	15.2	V
V _{SH2}		VSH2	VSH1=15V VSH2=5V	4.9	5	5.1	V
V _{SL}		VSL	VSL=-15V VCOM = -2V	-15.2	-15	-14.8	V
V _{COM}		VCOM	No waveform transitions. No loading. No RAM read/write No OTP read /write	-2.2	-2	-1.8	V

Table 10-2: Regulators Characteristics

Symbol	Parameter	Test Condition	Applicable pin	Min.	Тур.	Max.	Unit
IVSH	VSH1 current	VSH1 = +15V	VSH1	-	-	TBD	uA
IVSH1	VSH2 current	VSH2 = +5V	VSH2	-	-	TBD	uA
IVSL	VSL current	VSL = -15V	VSL	-	-	TBD	uA
IVCOM	VCOM current	VCOM = -2V	VCOM	-	-	TBD	uA

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11 AC Characteristics

11.1 Serial Peripheral Interface

SDA (Read Mode)

The following specifications apply for: VDDIO - VSS = 2.2V to 3.7V, Toph = 25°C, CL=20pF

Table 11-1: Serial Peripheral Interface Timing Characteristics

Write mode

Symbol	Parameter	Min	Тур	Max	Unit
fscL	SCL frequency (Write Mode)	-	-	20	MHz
tcssu	Time CS# has to be low before the first rising edge of SCLK	TBD	-	-	ns
tcshld	Time CS# has to remain low after the last falling edge of SCLK	TBD	-	-	ns
tcsнigh	Time CS# has to remain high between two transfers	TBD	-	-	ns
tsclhigh	Part of the clock period where SCL has to remain high	TBD	-	-	ns
tscllow	Part of the clock period where SCL has to remain low		-	-	ns
tsisu	Time SI (SDA Write Mode) has to be stable before the next rising edge of SCL		-	-	ns
tsihld	Time SI (SDA Write Mode) has to remain stable after the rising edge of SCL		-	-	ns

Read mode

Symbol	Parameter	Min	Тур	Max	Unit
f _{SCL}	SCL frequency (Read Mode)	1	-	2.5	MHz
tcssu	Time CS# has to be low before the first rising edge of SCLK	TBD	-	-	ns
tcshld	Time CS# has to remain low after the last falling edge of SCLK	TBD	-	-	ns
tсsнідн	Time CS# has to remain high between two transfers		-	-	ns
tsclhigh	Part of the clock period where SCL has to remain high		-	-	ns
tscllow	Part of the clock period where SCL has to remain low		-	-	ns
tsosu	Time SO(SDA Read Mode) will be stable before the next rising edge of SCL		TBD	-	ns
tsohld	Time SO (SDA Read Mode) will remain stable after the falling edge of SCL		TBD	-	ns

Note: All timings are based on 20% to 80% of VDDIO-VSS

tckper CS# tcshigh t sclhigh tcshld tcssu SCL → tsihld SDA (Write Mode) tsosu 🔾

 \leftrightarrow t_{SOHLD}

Figure 11-1: SPI timing diagram

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12 Application Circuit

C2 GDR RESE VSH2 VSH2 VSS C6 TSCI TSDA BS1 TSCL CONNECTION BUSY TSDA EXTERNAL TEMP SENSOR RES# D/C# 12 BS1 13 SCL BUSY SDA 14 15 CONNECTION VDDIO D/C# 16 MCU VCI CS# vss SCL 18 SDA 19 VPP 20 VSH1 VGH 22 23 VSL VSS VDD C0 VGL VCOM VPP C1 VSH1 VGH C5 VSL C7 VCOM C8

Figure 12-1: Schematic of SSD1685 application circuit

Table 12-1: Component list for SSD1685 application circuit

Part Name	Value	Requirements/Reference Part		
C0-C1	1uF	X5R/X7R; Voltage Rating : 6V or 25V		
C2-C7	1uF	0402/0603/0805; X5R/X7R; Voltage Rating : 25V		
C8	1uF	0402/0603/0805; X7R; Voltage Rating : 25V		
R1	2.2 ohm	0402/0603/0805; 1% variation, ≥ 0.05W		
D1-D3	Diode	MBR0530 1) Reverse DC voltage ≥ 30V 2) Io ≥ 500mA 3) Forward voltage ≤ 430mV		
Q1	NMOS	Si1304BDL/NX3008NBK 1) Drain-Source breakdown voltage \geq 30V 2) Vgs(th) = 0.9V (Typ), 1.3V (Max) 3) Rds on \leq 2.1 Ω @ Vgs = 2.5V		
L1	47uH	CDRH2D18 / LDNP-470NC lo= 500mA (Max)		
U1	0.5mm ZIF socket	24pins, 0.5mm pitch		

Remarks:

- 1) The recommended component value and reference part in Table 14-1 is subject to change depending on panel loading.
- 2) Customer is required to review if the selected component value and part is suitable for their application.

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The product(s) listed in this datasheet comply with Directive (EU) 2015/863 of 31 March 2015 amending Annex II to Directive 2011/65/EU of the European Parliament and of the Council as regards the list of restricted substances and People's Republic of China Electronic Industry Standard SJ/T 11363-2006 "Requirements for concentration limits for certain hazardous substances in electronic information products (电子信息产品中有毒有害物质的限量要求)". Hazardous Substances test report is available upon request.

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